Overview

HP ZBook Firefly 14" G11 Mobile Workstation PC



- 1. Ambient Light Sensor (Optional)
- 2. Internal Microphones (2)
- 3. Webcam LED (Optional)
- 4. Webcam
- 5. Camera Shutter
- 6. IR Camera (Optional)
- 7. IR Camera LEDs (Optional)

Right

- 8. Glass Clickpad
- 9. Power Button Key
- 10. Audio Combo Jack
- 11. SuperSpeed USB Type-A 5Gbps signaling rate (Charging)
- 12. Nano Security Lock Slot (Lock sold separately)
- 13. Nano SIM Card Slot (Optional)
- 14. Touch Fingerprint Sensor (Select models)



Overview



Left

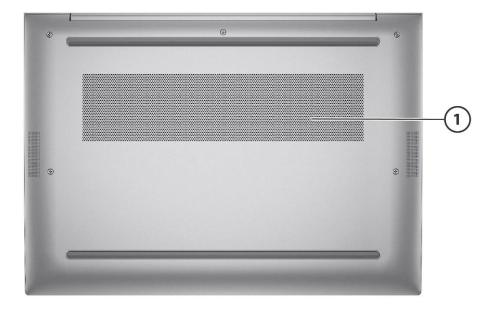
- 1. HDMI 2.1 Port (Cable not included)
- 2. SuperSpeed USB Type-A 5Gbps signaling rate
- 3. Thunderbolt[™] 4* with USB4 Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4)*

*SuperSpeed USB 20Gbps is not available with Thunderbolt[™] 4.

- Thunderbolt[™] 4* with USB4 Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4)*
- 5. LED Indicator
- 6. Smartcard Reader (Optional)



Overview



Bottom

1. Fan Venting



Overview

At A Glance

- Premium ultraslim design with precision-crafted all-metal chassis for a premium look and feel
- Intel[®] Core[™] Ultra5, Ultra7 U series and Intel Core Ultra5, Ultra7 H series Processors up to fourteen-core
- Preinstalled with Windows 11 versions or FreeDOS
- Now available paired with Intel Core Ultra5/Ultra7 H series processors and discrete graphics
- 16:10 ratio screen reduces the need to scroll by showing more vertical content than 16:9
- 5MP camera with 88° field of view allows you to move around more freely in front on the camera or accommodate a group
- DDR5-5600 memory with up to 64GB capacity
- Choice of displays:
 - o 35.6 cm (14") diagonal WUXGA IPS Anti-Glare LED-backlit, 300 nits, 45% NTSC
 - 35.6cm (14") diagonal WUXGA IPS Anti-Glare On-Cell LED-backlit touch, 300 nits, 45% NTSC
 - o 35.6 cm (14") diagonal WUXGA IPS Anti-Glare LED-backlit non-touch 400 nits, 100% sRGB
 - 35.6 cm (14") diagonal, WUXGA (1920 x 1200), Bent, LCD, UWVA, anti-glare, + Low Blue Light, Non-touch 800 nits, sRGB 100%, HP Sure View 5 integrated privacy screen
 - 35.6 cm (14") diagonal, WUXGA (1920 x 1200), Bent, LCD, UWVA, anti-glare, + Low Blue Light, Touch, 800 nits, sRGB 100%, HP Sure View 5 integrated privacy screen
 - o 35.6cm (14") diagonal WQXGA IPS Anti-Glare LED-backlit non-touch, 500 nits, 100% DCI-P3, DreamColor
- Optional NVIDIA RTX A500 pro graphics for improved performance for heavier graphics workloads.
- HP Wolf Security for Business creates a hardware-enforced, always-on, resilient defense.
- Optional 14" DreamColor display for complete color accuracy with a 120Hz refresh rate for smooth motion.
- Connectivity with optional HP 5G/WWAN available world-wide, and Thunderbolt[™] Docking (Dock sold separately)
- Undergoes MIL-STD 810H tests1
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles
- Designed to support all HP docking options including the HP Universal Dock G5

¹MIL-STD 810H is not intended to demonstrate fitness of U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Features

OPERATING SYSTEM

Preinstalled OS

Windows 11 Home 64 - HP recommends Windows 11 Pro for business¹ Windows 11 Home Single Language 64 - HP recommends Windows 11 Pro for business¹ Windows 11 Pro 64(Windows 11 Enterprise or Windows 10 Enterprise available with a Volume Licensing Agreement)¹ Windows 11 Pro¹ FreeDOS 3.0

¹ Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows[®] 8 or Windows 7 operating system on products configured with Intel[®] and AMD[®] 7th generation and forward processors or provide any Windows[®] 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

Name ^{1,2,3,4,5,7}	Cores Number o P-cores	Number of	Number of E-cores	Number Of LP E-core	Threads	L3 Cache	Max Turbo Frequency		Intel
		P-cores					P-cores	E-cores	SIPP/vPro® Enterprise
Intel® Core™ Ultra 7 processor 165H	16 cores	6	8	2	22	24 MB	5.00 GHz	3.80 GHz	Х
Intel® Core™ Ultra 7 processor 155H	16 cores	6	8	2	22	24 MB	4.80 Ghz	3.80 GHz	
Intel® Core™ Ultra 5 processor 135H	14 cores	4	8	2	18	18 MB	4.60 GHz	3.60 GHz	х
Intel® Core™ Ultra 5 processor 125H	14 cores	4	8	2	18	18 MB	4.50 GHz	3.60 GHz	
Intel® Core™ Ultra 7 processor 165U	12 cores	2	8	2	14	12 MB	4.90 GHz	3.80 GHz	Х
Intel® Core™ Ultra 7 processor 155U	12 cores	2	8	2	14	12 MB	4.80 GHz	3.80 GHz	
Intel® Core™ Ultra 5 processor 135U	12 cores	2	8	2	14	12 MB	4.40 Ghz	3.60 GHz	х
Intel® Core™ Ultra 5 processor 125U	12 cores	2	8	2	14	12 MB	4.30 Ghz	3.60 GHz	

PROCESSOR



Features

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

³ Intel vPro[®] requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro[®] Essentials and Enterprise vary. See http://intel.com/vpro

⁴ In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

⁵ Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

⁷Features and software that require a NPU may require software purchase, subscription or enablement by a software or platform provider, and third party software may have specific configuration or compatibility requirements. Performance varies by use, configuration, and other factors.

CHIPSET

Chipset is integrated with processor

GRAPHICS

Integrated

Intel[®] Arc[™] Pro Graphics (H Series processors)³

Intel® Graphics (U Series processors)

Discrete

NVIDIA RTX[™] A500 Laptop GPU (4 GB GDDR6 dedicated)^{1,2}

Supports

Support HD decode, DX12, HDMI 2.1, HDCP 2.3

¹ Both UMA & Discrete configurations support 4 independent displays when on the HP Thunderbolt Dock G4 (120W) (sold separately) - Max. resolution = 2.5K @60Hz (DP1) & 2.5K @60Hz (DP2) & FHD (VGA) OR 4K @60Hz (one DP Port) & 4K @60Hz (Type-C output port using a Type C-to-DP adapter).

² HDMI cable Sold Separately

³ Intel[®] Arc[™] Pro Graphics only available on select Intel[®] Core[™] Ultra H-series processor-powered systems with at least 16GB of system memory in dual channel configuration.

DISPLAY

Non-touch



Features

- 35.6 cm (14") diagonal, WUXGA (1920 x 1200), Bent, LCD, UWVA, anti-glare, + Low Blue Light, 800 nits, sRGB 100%, HP Sure View 5 integrated privacy screen^{1,3,4,5}
- 35.6 cm (14") diagonal, WQXGA (2560 x 1600), Bent, LCD, 120Hz, UWVA, anti-glare, WLED, 500 nits, DCI-P3 100%, HP DreamColor^{1,3}
- 35.6 cm (14") diagonal, WUXGA (1920 x 1200), Bent, LCD, UWVA, anti-glare, WLED + Low Blue Light, 400 nits, low power, sRGB 100%^{1,3}
- 35.6 cm (14") diagonal, WUXGA (1920 x 1200), Bent, LCD, UWVA, anti-glare, WLED, 300 nits, NTSC 45%^{1,3}

Touch

- 35.6 cm (14") diagonal, WUXGA (1920 x 1200), Bent, LCD, touch, anti-glare, WLED, 300 nits, NTSC 45%^{1,3,4,5}
- 35.6 cm (14") diagonal, WUXGA (1920 x 1200), Bent, LCD, UWVA, anti-glare, + Low Blue Light, 800 nits, sRGB 100%, HP Sure View 5 integrated privacy screen^{1,3,4,5}

Displays support

Supports dual display through the dock For more information, please reference the following ZBook docking whitepaper: https://h20195.www2.hp.com/v2/GetDocument.aspx?docname=4AA5-2657ENW

Display Size

14" 35.56 cm (14")

¹HD content required to view HD images.

³Resolutions are dependent upon monitor capability, and resolution and color depth settings. ⁴HP Sure View 5 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.

⁵Actual brightness will be lower with touchscreen or Sure View.



Features

DOCKING	l
---------	---

DUCKING	
Docking station model #1	HP Thunderbolt 120W G4 Dock
Total number of supported displays (incl.the notebook) display)	4
Max.resolutions supported	Quad 4K @60Hz Dual 8K single cable@30 for TB hosts or USB-C hosts DP 1.4 with DSC in high res mode
Dock Connectors	2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode
Technical limitations	Thunderbolt Hosts: Maximum of (4) displays with maximum resolution of 5K@ 30Hz running Thunderbolt host. Max resolution possible is dual 8K displays @ 60Hz running Thunderbolt host or running a non-Thunderbolt host in High Resolution mode @30Hz Non-Thunderbolt hosts: The highest resolution for dual displays running a non-Thunderbolt host in multi-function mode is (1) 5K dual cable (using both DP ports) +(1) 4K on USB-C DP port Non-Thunderbolt hosts support (3) displays with a max resolution of: (2) 5K single cable + (1) 4K UHD @ 60 Hz in high resolution mode. In multi-function mode the maximum resolution for (3) displays is (2) 5K single cable @ 30Hz + (1) 4K UHD @ 30Hz.
Docking station model #2	HP USB-C Dock G5
Total number of supported displays (incl.the notebook) display)	3
Max.resolutions supported	Dual 5K@ 30Hz + (1) 4K UHD (multi-function mode)
Dock Connectors	1xHDMI, 2xDP
Technical limitations	Highest resolution with dual displays is two 8K@ 60Hz host in High Resolution mode. Three maximum displays supported are two 5K@ 30 Hz on DP ports plus one 4K UHD@ 30 Hz on HDMI in multi-function mode The highest resolution for a non-Thunderbolt host in Multi-function mode is a single 5K dual cable (using both DP ports) + (1) 4K on HDMI port.
Docking station model #3	HP USB-C/A Universal Dock G2
Total number of supported displays (incl.the notebook) display)	3
Max.resolutions supported	Triple 4K UHD@ 60Hz
Dock Connectors	1xHDMI, 2xDP
Technical limitations	The best resolution for dual or triple displays is 4K UHD@ 60Hz. For use with the USB-A adapter that comes in the box the maximum number of displays supported is (2) 4k x 60 Hz on the Type-A Gen 1 connection from the host

Features

STORAGE AND DRIVES*

PCIe[®] NVMe[™] M.2 2280 Storage

2 TB PCIe[®] Gen4x4 NVMe[™] SSD Three Layer Cell 1 TB PCIe[®] Gen4x4 NVMe[™] SSD Three Layer Cell 1 TB PCIe[®] NVMe[™] SSD Value 512 GB PCIe[®] Gen4x4 NVMe[™] Seld Encrypted OPAL2 SSD Three Layer Cell 512 GB PCIe[®] Gen4x4 NVMe[™] SSD Three Layer Cell 512 GB PCIe[®] NVMe[™] SSD Value 256 GB PCIe[®] NVMe[™] Seld Encrypted OPAL2 SSD Value 256 GB PCIe[®] NVMe[™] SSD Value

* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35GB of disk is reserved for system recovery software.

MEMORY

Maximum Memory 64GB DDR5-5600 Memory 64GB DDR5-5600 (2x32GB) 32GB DDR5-5600 (2x16GB) 32GB DDR5-5600 (1x32GB) 16GB DDR5-5600 (1x16GB) 8GB DDR5-5600 (1x8GB)

Memory Slots

2 SODIMM DDR5 SODIMMS, system runs at 5600 Supports Dual Channel Memory

NOTE: Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.



Features

NETWORKING/COMMUNICATIONS

WLAN

Intel® AX211 Wi-Fi 6E Bluetooth® 5.3 wireless card vPro WLAN^{1,2} Intel® AX211 Wi-Fi 6E Bluetooth® 5.3 wireless card WLAN¹

¹Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, and Windows 11 to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.

² Intel vPro[®] requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro[®] Essentials and Enterprise vary. See http://intel.com/vpro

WWAN

HP 5G Sub-6 Cat 19 WWAN eSIM^{1,2} HP 4G LTE-A Pro Cat 16 WWAN eSIM¹

¹WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

²5G module is optional and must be configured at the factory. Module designed for 5G NR NSA (non-standalone) networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP. Module requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Data connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select platforms and select countries, where carrier supported.

LPWAN

Qualcomm[®] 9205

Near Field Communication (NFC) module

NFC NXP NPC300¹

¹Sold separately or as an optional feature.

Miracast Native Miracast Support

NOTE: Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.

AUDIO/MULTIMEDIA

Audio

Audio Tuning by Poly Studio 2 Integrated stereo speakers Discrete Amplifiers 2 Integrated dual array microphone 3.5mm Headset: CTIA only; Headphone-out

Speaker Power 1W/80hm Per speaker



Features

Camera¹

5MP+Infrared camera 5MP camera

Sensors

ALS (ambient light sensor) ACS (Adaptive Color Sensor) Hall effect Sensor Thermal Sensor HP Tamper Lock²

¹ Sold separately or as an optional feature.
 ² HP Tamper Lock must be enabled by the customer or your administrator.



Features

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard*

HP Premium Keyboard, spill-resistant, Privacy, Backlit, Durakey keyboard. HP Premium Keyboard, spill-resistant, Backlit, Durakey keyboard. HP Premium Keyboard, spill-resistant, Durakey keyboard.

Pointing Devices

Clickpad with multi-touch gesture support Microsoft Precision Touchpad Default Gestures Support Multi-touch gesture support

Function Keys

ESC: system information F1 - Display Switching F2 - Blank or Privacy F3 - Brightness Down F4 - Brightness Up F5 - Audio Mute F6 - Volume Down F7 - Volume Up F8 - Mic Mute F9 - Blank or Backlit Toggle F10 - Insert F11 - Airplane Mode F12 - HP Command Center home end Power Button (with LED) Delete Microsoft Copilot key** **Hidden Keys** Fn+R - Break Fn+S - Svs Ra Fn+C - Scroll Lock

*Backlit keyboard is an optional feature.

**Requires Windows 11 and an NPU. Timing of feature delivery and availability varies by market and device. Requires Microsoft account to log in. Where Copilot in Windows is not available, the Copilot key will lead to the Bing search engine. See http://aka.ms/WindowsAIFeatures

SOFTWARE AND SECURITY

Software

Bing Search for IE11 Buy Microsoft Office (Sold separately) HP Connection Optimizer¹⁰ HP Easy Clean² HP Easy Clean Keyboard Driver² HP Hotkey Support HP Mac Address Manager HP Notifications HP PC Hardware Diagnostics UEFI HP PC Hardware Diagnostics Windows HP Privacy Settings HP Support Assistant¹



Features

HSA Fusion for Commercial HPX for CMIT Battery Health Manager⁵

Manageability Features

HP Client Catalog (download) HP Client Management Script Library (download) HP Cloud Recovery²⁸ HP Connect for Microsoft Endpoint Manager²⁶ HP Driver Packs (download) HP Image Assistant Gen5 (download) HP Manageability Integration Kit (download)¹² HP Patch Assistant (download)²⁷

Security Management

HP Wolf Security of Business²⁹ includes:

HP Client Catalog (download) HP Client Management Script Library (download) HP Cloud Recovery²⁸ HP Connect for Microsoft Endpoint Manager²⁶ HP Driver Packs (download) HP Image Assistant Gen5 (download) HP Manageability Integration Kit (download)¹² HP Patch Assistant (download)²⁷ Wolf Pro Security²⁵

Security- TPM

Model: Nuvoton NPCT760HABYX TCG TPM 2.0 Version: 7.2.3.1 FIPS 140-2 Compliant: Yes

Model: Infineon SLB9672VU2.0 FW15.23 TCG TPM 2.0 Version: 15.23 FIPS 140-2 Compliant: Yes

BIOS

Absolute Persistence Module⁷ BIOS Update via Network HP BIOSphere Gen6⁶ HP DriveLock & Automatic DriveLock HP Fingerprint Sensor³² HP Secure Erase¹⁷ HP Wake on WLAN

Smartcard Reader

Model number: Alcorlink AK9563 FIPS 201 Compliant: Yes

¹ HP Support Assistant - Requires Windows and Internet Access.

²HP Easy Clean requires Windows 10 RS3 and higher and will disable the keyboard, touchscreen, and clickpad only. Ports are not disabled. See user guide for cleaning instructions.

⁵ Depending on the version available for your device and the setting you select, HP Battery Health Manager (BHM) will use a proprietary set of algorithms to optimize battery health during the life of the battery. New Commercial Notebooks come equipped with BHM set to "Let HP



Features

Manage My Battery Health" as the default. This setting will reduce charge capacity over time to optimize battery health and mitigate factors that can accelerate battery degradation. As a result of this reduction, battery runtime will decrease over time as available charge capacity is reduced. HP may, at any time, update HP Battery Health Manger to improve available settings, functionality, and performance. Refurbished products may have customized default settings to optimize user experience. For additional information on updating or modifying HP Battery Health Manager settings, please go to HP.COM/SUPPORT/BATTERY.

⁶ HP BIOSphere Gen6 is available on select HP Pro, Elite and ZBook PCs. See product specifications for details. Features may vary depending on the platform and configurations.

⁷ Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:

http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software. ¹⁰ HP Connection Optimizer requires Windows 10 and Windows 11.

¹² HP Manageability Integration Kit can be downloaded from https://ftp.ext.hp.com/pub/caps-softpaq/cmit/HPMIK.html.
 ¹⁷ HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.

²⁵ HP Wolf Pro Security Edition is available preloaded on select SKUs, and, depending on the HP product purchased, includes a license with a term length communicated to you at purchase and in your order confirmation email. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software - End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish_3875769-3873014-16 as that EULA is modified by the following: 7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition is effective upon 4 months after the date the HP Product was shipped by HP and will continue for the term communicated to you at purchase and in your order confirmation email ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support. Notwithstanding the foregoing, the license shall expire no later than one year after the fixed term of the subject license ends.

²⁶ HP Connect for Microsoft Endpoint Manager is available from the Azure Market Place for HP Pro, Elite, Z and Point-of-Sale PCs managed with Microsoft Endpoint Manager. Subscription to Microsoft Endpoint Manager required and sold separately. Network connection required.
²⁷ HP Patch Assistant available on select HP PCs with the HP Manageability Kit that are managed through Microsoft System Center Configuration Manager. HP Manageability Integration Kit can be downloaded from

http://www8.hp.com/us/en/ads/clientmanagement/overview.html.

²⁸ HP Cloud Recovery is available for Z by HP, HP Elite and Pro desktops and laptops PCs with Intel[®] or AMD processors and requires an open, wired network connection. **NOTE:** You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630.

²⁹ HP Wolf Security for Business requires Windows 10 Pro or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features and OS requirement.

³² HP Fingerprint Reader is an optional feature that requires Windows 10 IoT and must be configured at purchase.



Features

POWER

Power Supply

HP Standard 65W USB Type-C[®] adapter² HP Slim 65W USB Type-C[®] adapter² HP Slim 100W USB Type-C[®] AC adapter^{2,5}

Battery

HP Long Life 3-cell, 56 Whr Polymer^{3,4}

Battery Recharge Time

Supports battery HP Fast Charge: approximately 50% in 30 minutes⁶

Power Cord

3-wire plug - 1m 2-wire plug - 1m

Battery life

UMA¹

Up to 15 hours and 15 minutes with 56whr battery (HP Long Life 3-Cell, 56 Whr Polymer, UMA graphic, Intel Ultra 7 U15 vPro, Display set to 250 nits display (on a 400-nit display), 2*8G DDR5 memory, 256 GB SSD)

Up to 14 hours with 56whr battery (HP Long Life 3-Cell, 56 Whr Polymer, UMA graphic, Intel Ultra 7 H28 vPro, Display set to 250 nits display (on a 400-nit display), 2*8G DDR5 memory, 256 GB SSD)

Discrete¹

Up to 9 hours and 45 minutes with 56whr battery (HP Long Life 3-Cell, 56 Whr Polymer, NVIDIA RTX A500 graphics, Intel Ultra 7 H28 vPro, Display set to 250 nits display (on a 400-nit display), 2*8G DDR5 memory, 256 GB SSD)

¹ MM25 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See www.bapco.com for additional details.

² Availability may vary by country.

³Battery is internal and not replaceable by customer. Serviceable by warranty.

⁴ For new batteries, actual battery Watt-hours (Wh) may differ from the design capacity and may have a full charge capacity that differs by up to 10, which is typical for lithium-ion batteries. Battery capacity naturally decreases over time and with use, depending on several factors such as battery health management settings, shelf life, temperature, environment, loaded apps, features, system configuration, and power settings.

⁵ The 100w AC adapter is required when discrete graphics are used.

⁶ Recharges your battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter minimum of 65 watts required for battery capacities 56Whr or less. Power adapter minimum of 100 watts required for battery capacities greater than 56Whr and less than 83Whr. Power adapter minimum of 120 watts required for battery capacities greater than 83Whr and less than 100Whr. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance



Features

WEIGHTS & DIMENSIONS

Dimensions (w x d x h) 12.42 x 8.82 x 0.76 in 31.56 x 22.435 x 1.92 cm

Weights* Product Weight- 56Whr Starting at 3.13 lb Starting at 1.418 kg

*Weight will vary by configuration. Does not include power adapter.

PORTS/SLOTS

Left side

2 Thunderbolt[™] 4 with USB4 Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4) *

- 1 HDMI 2.1**
- 1 Super Speed USB Type-A 5Gbps signaling rate
- 1 Smartcard reader

Right side

- 1 Headphone/microphone combo jack
- 1 Nano SIM card slot
- 1 Super Speed USB Type-A 5Gbps signaling rate
- 1 Security Lock Slot

*SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4. **HDMI cable sold separately.

SERVICE AND SUPPORT

1-year warranty and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty.. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.

¹HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

Certification and Compliance

CSA/UL 62368-1
ENERGY STAR®
FCC/ICES/CISPR/VCCI
CE MARKING
GS Mark



Features

China CCC/SRRC Taiwan BSMI/NCC Korea KCC/KC/KES Ukraine NSoC/TEC EAEU Compliance Saudi Arabian Compliance TCO EPEAT® registered* Low Blue Light WW RoHS

Sustainable Impact Specifications

Low Halogen** aligned with HP GSE

*Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. EPEAT[®] status varies by country. Visit www.epeat.net for more information

**External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.

SYSTEM UNIT

Requirements (AC Power)VoltageAverage Operating Power(idle)Average Operating Power(idle)Integrated graphicsYesDiscrete GraphicsN/AMax Operating Power65WTemperatureOperatingOperating32° to 95° F (0° to 35° C)Relative HumidityOperatingIntegrated graphics10% to 90%, non-condensing
Discrete GraphicsN/AMax Operating Power65WTemperatureOperatingNon-operating-4° to 140° F (-20° to 60° C)
Max Operating Power 65W Temperature Operating 32° to 95° F (0° to 35° C) Non-operating -4° to 140° F (-20° to 60° C)
Temperature Operating 32° to 95° F (0° to 35° C) Non-operating -4° to 140° F (-20° to 60° C)
Non-operating -4° to 140° F (-20° to 60° C)
Relative Humidity Operating 10% to 90%, non-condensing
Non-operating 5% to 95% (38.7° C (101.6° F) maximum wet bulb tempera-ture; non-condensing)
Shock Operating 40 G, 2 ms, half-sine
Non-operating 240 G, 2 ms, half-sine
Random Vibration Operating 1.043 grms
Non-operating 3.5 grms
Maximum AltitudeOperating10,000 ft (3,048 m)
(unpressurized) Non-operating 40,000 ft (12,192 m)
Planned Industry Standard Regulatory Model HSN-145C-4 Certifications Number
CSA/UL 62368-1 Yes
ENERGY STAR®1 Yes
FCC/ICES/CISPR/VCCI Yes
CE MARKING Yes
GS Mark Yes
China CCC/SRRC Yes
Taiwan BSMI/NCC Yes
Korea KCC/KC/KES Yes





Features

Ukraine NSoC/TEC	Yes
EAEU Compliance	Yes
Saudi Arabian Compliance	Yes
TCO	Yes
EPEAT [®]	EPEAT [®] Gold in the United States ²
Low Blue Light	Yes
WW RoHS	Yes
Saudi Arabian	
Compliance (ICCP)	Yes
SABS	Yes

¹Configurations of the HP ZBook Firefly 14" G11 Mobile Workstation PC that are ENERGY STAR[®] qualified are identified as HP ZBook Firefly 14" G11 Mobile Workstation PC ENERGY STAR on HP websites and on http://www.energystar.gov. ²Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. Status varies by country. Visit www.epeat.net for more information.



Technical Specifications – Displays

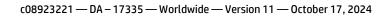
DISPLAYS

14 in WUXGA (1920 x 1200) Anti-Glare UWVA LED NTSC 45 NB2X 300 eDP 1.2 w/o PSR bent LCD Panel

Outline Dimensions (W × H)	307.29 x 199.25 (max)	
Active Area	301.59 X 188.50 (typ)	
Weight	300 (max)	
Diagonal Size	14	
Thickness	3.0 / 4.8 (max)	
Interface	eDP 1.2	
Surface Treatment	Anti-Glare	
Touch enabled	No	
Contrast Ratio	1000:1(typ)	
Refresh Rate	60 Hz	
Brightness	300 nits	
Pixel Resolution	Pitch	1920 x 1200 (WUXGA)
	Format	RGB
Backlight	WLED	
Color Gamut Coverage	NTSC 45%	
Color Depth	6+2 FRC	
Viewing Angle	UWVA 89/89/89/89	
Low Blue Light	No	
Power Consumption (W, EBL@ 150nits max/ 200nits max)	2 20 (may) / 2 70 (may	A
111a <i>x)</i>	2.20 (max) / 2.70 (max)	

*All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

14 in WUXGA (1920 x 1200) Anti-Glare UWVA LED NTSC 45 NB2X 300 TOP eDP 1.2 w/o PSR bent LCD Panel	Outline Dimensions (W × H) Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch enabled Contrast Ratio	307.29 x 199.25 (max) 301.59 x 188.50 (typ) 305g (max) 14 3.0 / 5.0 (max) eDP 1.2 Anti-Glare Yes 1000:1(typ)	
	Refresh Rate Brightness Pixel Resolution Backlight Color Gamut Coverage Color Depth Viewing Angle Low Blue Light	60 Hz 300 nits Pitch Format WLED NTSC 45% 6+2 FRC UWVA 89/89/89/89 No	1920 x 1200 (WUXGA) RGB





Technical Specifications – Displays

Power Consumption (W, EBL@ 150nits max/ 200nits max)

2.15 (max)/2.65 (max)

*All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

14 in WUXGA (1920 x
1200) Anti-Glare UWVA
WLED+LBL sRGB NB2X
400 eDP 1.4+PSR2 Low-
Power 100 bent LCD
Panel

Outline Dimensions (W \times H)	307.590 x 199.550 (max	<)
Active Area	301.590 X 188.500 (typ))
Weight	210 (max)	
Diagonal Size	14	
Thickness	2.0 / 3.8 (max)	
Interface	eDP 1.4	
Surface Treatment	Anti-Glare	
Touch enabled	No	
Contrast Ratio	1000:1(typ)	
Refresh Rate	60 Hz	
Brightness	400 nits	
Pixel Resolution	Pitch	1920 x 1200 (WUXGA)
	Format	RGB
Backlight	WLED	
Color Gamut Coverage	sRGB 100%	
Color Depth	8 bits	
Viewing Angle	UWVA 89/89/89/89	
Low Blue Light	Yes	
Power Consumption (W, EBL@ 150nits max/ 200nits max)	1.29 (max) / 1.66 (max)	

*All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

14.0 in WUXGA (1920 x 1200) Anti-Glare UWVA Low Blue Light sRGB 100 800 eDP 1.4+PSR+IOL Sure View 5 bent LCD Panel	Outline Dimensions (W x H)	306.890 x 197.900 (ma	ax)	
	Active Area	301.590 X 188.500 (ty	p)	
	Weight	260 (max)		
	Diagonal Size	14		
	Thickness	2.2 / 3.9 (max)		
	Interface	eDP 1.4		
	Surface Treatment	Anti-Glare		
	Touch Enabled	No		
	Contrast Ratio	1500:1(typ)		
	Refresh Rate	60 Hz		
	Brightness	800 nits		
	Pixel Resolution	Pitch	1920 x 1200 (WUXGA)	
		Format	RGB	



Technical Specifications – Displays

Backlight	WLED
Color Gamut Coverage	sRGB 100%
Color Depth	8 bits
Viewing Angle	UWVA 89/89/89/89
Low Blue Light	Yes
Power Consumption (W, EBL@ 150nits max/ 200nits max)	1.48 (max)/1.8(max)

*All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

14.0 in WUXGA (1920 x 1200) Anti-Glare UWVA Low Blue Light sRGB 100	Outline Dimensions (W x H)	306.890 x 197.900 (ma	(xı
	Active Area	301.590 X 188.500 (typ	o)
800 eDP 1.4+PSR+IOL	Weight	260 (max)	
Sure View 5 bent LCD	Diagonal Size	14	
Panel	Thickness	2.4 / 4.2 (max)	
	Interface	eDP 1.4	
	Surface Treatment	Anti-Glare	
	Touch Enabled	Yes	
	Contrast Ratio	1500:1(typ)	
	Refresh Rate	60 Hz	
	Brightness	800 nits	
	Pixel Resolution	Pitch	1920 x 1200 (WUXGA)
		Format	RGB
	Backlight	WLED	
	Color Gamut Coverage	sRGB 100%	
	Color Depth	8 bits	
	Viewing Angle	UWVA 89/89/89	
	Low Blue Light	Yes	
	Power Consumption (W, EBL@ 150nits max/ 200nits max)	1.60 (max)/1.97(max)	
	*All specifications represent t	he typical specifications	provided by HP's component m

*All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

14 in WQXGA DRM (2560 x 1600) Anti-Glare UWVA LED DCI-P3 NB2X 500 eDP 1.4+PSR2 100 120Hz bent LCD Panel	a Outline Dimensions (W x H)	307.594 x 199.546 (max)
	Active Area	301.594 x 188.496 (typ)
	Weight	230 (max)
	Diagonal Size	14
	Thickness	2.0 / 3.8 (max)
	Interface	eDP 1.4
	Surface Treatment	Anti-Glare
	Touch Enabled	No

Technical Specifications – Displays

Contrast Ratio	1200:1(typ)	
Refresh Rate	120 Hz	
Brightness	500 nits	
Pixel Resolution	Pitch	2560 x1600 (WQXGA)
	Format	RGB
Backlight	WLED	
Color Gamut Coverage	DCI-P3 100%	
Color Depth	8 bits	
Viewing Angle	UWVA 89/89/89/89	
Low Blue Light	No	
Power Consumption (W, EBL@ 150nits max/ 200nits max)	2.88 (max) / 3.44 (max)	

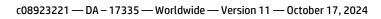
*All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



Technical Specifications – Storage

STORAGE AND DRIVES

3-bit Statu 2:200 FCle Form Factor NL2:2200 VeN WMe Three Layer Cle Vel WMe Three Layer Cle Vel WMe Three Layer Cle Width 0.09 in (2.2 mm) Width 0.02 ib (10 g) Interface PCle NVMe 6en4X4 Performance Minimum Sequential Read Minimum Sequential Read A gold Blocks 1,000,215,215 3500 MB/s 220% Departing Temperature 2% to 108% (200 mag) 3 500 MB/s 220% Features Pyrite 2.0; TRIM; L1.2 NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatic dapactivis loss. Up to 3/5 G (for Windows 11) is reserved for system recovery software. SSD 1TB 2280 PCle-40x4 Form Factor M.2 2280 WWe Three Layer Cett Form Factor M.2 2280 WMMe Three Layer Cett Gapacity TB NAND Type TLC Height 0.09 in (2.3 mm) Width 0.39 in (2.2 mm) Width 0.87 in (2.9 mm) Width 0.87 in (2.2 mm) Source Source Width 0.97 in (2.3 mm) Viet (2 mm) Viet (2 mm) Width 0.97 in (2.2 mm)	SSD 512GB 2280 PCIe-	Form Factor	M.2 2280		
Cell Capacity STEC Height 0.09 in (2.3 mm) U Width 0.02 ib (10 g) U Interface PCIe NVMe Gen4X4 Performance Performance Minimum Sequential Read Minimum Sequential Write G00 MB/s ± 20% 3500 MB/s ± 20% S500 MB/s ± 20% Deperating Temperature 32" to 158" f 0" to 70"C) [ambient temp] Performance Features Prife 2.0, TRM; L1.2 NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 11) is reserved for system recovery software. SSD 1TB 2280 PCIe-4x4 Form Factor M.2 2280 NVMe Three Layer Cell Form Factor M.2 2280 Width 0.02 ib (10 g) Interface Height 0.09 in (2.3 mm) U Width 0.87 in (22 mm) U Width 0.82 ito 158" (0" to 70"C) [ambient temp] Features Poine 2.0, TRM; L1.2 NUME Three Layer Cell Rod MB/s ± 20% Vieight 0.02 bit (10 g) Interface Interface POIN VME Gen4X4 Portor Performance Minimum Sequential Write	4x4 NVMe Three Layer				
NVMe Three Layer Cell Note: The State S					
Nich0.87 in (22 mm)Weigh0.02 lb (10 g)HerfacePCINVB Gen4X4PerformanceMinium Sequential RealMinium Sequential RealMinium Sequential WriteGoto MJS - 20%3500 MJS + 20%Deperting Temperatua32' to 158" (0' to 70"C) (amistre temp)FeaturesPrite 2.01 RIN; L1.2NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Attain system recovery software.SSD 1TB 2280 PCI-444M2 2280NUME Three Layer CellCapacityMAND TypeM.2 2280Height0.09 in (2.3 mm)Width0.93 in (2.2 mm)Width0.93 in (2.2 mm)Minium Sequential Write100 in (0.3 mm)Weight0.02 lb (10 g)InterfacePerformanceQue and Minium Sequential Write2000 MIDS ± 20%Forting Temperatua2.000,409,264Logical Blocks0.900 MIDS ± 20%Operating Temperatua2.100 Sign (2.1 mm)FeaturesMOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Attain formated capacity is less. Up to 55 G (for Windows 11) is reserved for system recovery software.SSD 27B 2280 PCI-444PerformanceNice (MAND Sign (2.1 mm)Nice Rating TemperatuaA2280Solon MIDS ± 20%Nice Rating TemperatuaA2280Solon MIDS ± 20%Nice Rating TemperatuaMinium Sequential Write data (2.1 mm)FeaturesPerformanceNice (2.1 mm)Nice Rating TemperatuaA2280Solon MIDS ± 2.0 mm)Nice Rating Tempera					
Weight 0.02 b (10.9) Interface PCIe NUMe Gen4X4 Performance Minimum Sequential Read Minimum Sequential Write 6400 MB/s ± 20% 3500 MB/s ± 20% Logical Blocks 1,000,215,215 0perating Temperature 22' to 158PF (0' to 70''O) (ambient temp) Features Pyrite 2.0; TRIM; L1.2 NOTE: For storage drives, GB = 1 billion bytes, TB = 1 trillion bytes, Actual formatted capacity is less. Up to 35 GB (for Windows 11) is reserved for system recovery software. SSD 1TB 2280 PCIe-4x4 Form Factor M.2 2280 NVME Three Layer Cell Form Factor M.2 2280 NAND Type TLC		-			
Interface PcIe NW8 Gen4X4 Performance Minimus Sequential Real Minimus Sequential Real Iogical Blocks 1,000,215,215 Operating Temperature 2*10 158*f (0*10 70*C) [amiiuters] Features OTE: For storage drives, Ge I - billion bytes, TB = 1 trillion bytes, Artual formatted capacity is less. U = 0.5 GB (for Windows 11) is reserved for system recovery software. SSD 1TB 2280 PCIe-44% Form Factor M.2 2280 NNME Three Layer Cell Form Factor M.2 2280 NAND Type TC					
Performance Minimu Sequential ead Minimu Sequential ead 6400 Mb/s ±20% 3500 MB/s ±20% Logical Blocks 20:015/5 (05 070°L0 + UTM)] Operating Tempereta 20:015/81 (05 070°L0 + UTM)] Fetures Prite 20:178 (05 070°L0 + UTM)] Fetures Prite 20:178 (05 070°L0 + UTM)] Fetures Prite 20:178 (05 070°L0 + UTM)] NVME Three Layer Cal NOTE: For storage drives, GB + 1 billion bytes. TB = 1 trillion bytes. Atual of minuted capacity is less. Voi 35 GB (for Windows 11) is reserved for system recovery software. SSD 1TB 2280 PCIe-440 Form Factor N.2 2280 NVME Three Layer Cal Capacity 100 (01 (23 mm)) MAND Type TC 100 (01 (23 mm)) NUME Three Layer Cal Note (04 (04 (04 (04 (04 (04 (04 (04 (04 (04		•	-		
SSD 1TB 2280 PCIe-440 NVMe Three Layer Cell SSD 1TB 2280 PCIe-440 NVMe Three Layer Cell Norm Factor NVMe Three Layer Cell NAND Type NVMe Three Layer Cell NAND Type NUT First Type NUT NAND Type NUT First Type NUT NAND Type NUT First Type NUT NAND Type NUT First Type NUT NUT First Type NUT NUT NUT First Type NUT NUT NUT NUT NUT NUT NUT NUT NUT NUT				Minimum Computiel Intrite	
Logical Blocks 1,000,215,215 Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features Pyrite 2.0; TRM; L1.2 NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 11) is reserved for system recovery software. SSD 1TB 2280 PCIe-444 Form Factor M.2 2280 NVMe Three Layer Cell Form Factor M.2 2280 Minimu Sequential Minimus 0.09 in (2.3 mm) Using 1.2 mm) Wigith 0.09 in (2.3 mm) Using 1.2 mm) Wigith 0.02 lb (10 g) Using 1.2 mm) Weight 0.02 lb (10 g) Using 1.2 mm) Interface Pcle NVMe Gen4X4 S000 MB/s ±20% Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features Pyrite 2.0; TRM; L1.2 S000 MB/s ±20% Interface Pyrite 2.0; TRM; U1.2 S000 MB/s ±20% Features Pyrite 2.0; TRM; U1.2 S000 MB/s ±20% Moreting Temperat		Performance	•	-	
SSD 1TB 2280 PCIe-447 Features Pyrite 2.0; TRIM; L1.2 NDTE: For storage drives, GB = 1 billion bytes, TB = 1 trillion bytes, Actual formatted capacity is less. Up to 35 GB (for Windows 11) is reserved for system recovery software. SSD 1TB 2280 PCIe-447 Form Factor M.2 2280 NNMe Three Layer Cell Gapacity TB MAND Type TC Height 0.09 in (2.3 mm) Width 0.47 in (22 mm) Jenetation Sector Secto		Logical Blocks	1.000.215.215		
SSD 1TB 2280 PCIe-4x4 NVMe Three Layer Cell Form Factor M.2 2280 Gapacity TIB NAND Type TLC Height 0.02 lb (10 g) Interface PCIe NVMe Gen4X4 Performance NC2 zmm) Width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCIe NVMe Gen4X4 Performance Minimum Sequential Read Minimum Sequential Write Gapacity 32° to 158° (0° to 70°C) [am/Lim Lim Lim Lim Lim Lim Lim Lim Lim Lim		-		vient temp]	
SSD 1TB 2280 PCIe-4x4 NVMe Three Layer Cell Form Factor M.2 2280 Capacity 1TB NAND Type Height 0.09 in (2.3 mm) Jamma Weight 0.02 in (2.0 mm) Jamma Jamma Operating Temperature S000 MB/s ±20% Cogical Blocks 2,000,409,264 S000 MB/s ±20% Operating Temperature 32* to 158* F (0* to 70*C) [amJient temp] Features Pyrite 2.0; TRIM; L1.2 NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 11) is reserved for system recovery software. SSD 2TB 2280 PCIe-4x4 Form Factor M.2 2280 MNME Three Layer Cell Form Factor M.2 2280 Capacity ZTB ZTB NAND Type TLC Jamma					
NVMe Three Layer CellCapacityTBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Wight0.02 lb (10 g)InterfacePCle NVMe Gen4X4PerformanceMinium Sequential RealMinium Sequential WriteIngerating Temperature92 vol 0.09/2645000 MB/s ± 20%PertormancePyrite 2.0; TRIN; L1.2Sol 0.00 MB/s ± 20%FeaturesPyrite 2.0; TRIN; L1.2NOTE: For storage drives, GB + 1 billion bytes. TB + 1 trillion bytes. Actual formatted capacity is less. Up - 3 s GB (for Windows 11) is reserved for system recovery software.SSD 2TB 2280 PCle-4447Form FactorM.2 2280NVME Three Layer CellForm FactorM.2 2280NVME Three Layer CellCapacityCapacitySIS 2TB 2280 PCle-4447NVME Three Layer CellForm FactorM.2 2280NUME Three Layer CellCapacityCapacitySIS 2TB 2280 PCle-444NUME Three Layer CellCapacityCapacityNUME Three Layer CellForm FactorM.2 2280NUME Three Layer CellCapacityCapacitySIS 2TB 2280 PCle-444NUME Three Layer CellCapacityCapacityNUME Three Layer CellCapacityCapacitySIS 2TB 2280 PCle-444NUME Three Layer CellCapacityCapacitySIS 2TB 2280 PCle-444NUME Three Layer CellCapacityCapacitySIS Cattor CellNUME Three Layer CellCapacityCapacitySIS Cattor CellNUME Three Layer CellCapacityCapacity <th></th> <th></th> <th>NOTE: For storage drives, GB formatted capacity is less. Up</th> <th></th>			NOTE: For storage drives, GB formatted capacity is less. Up		
NAND Type NAND Type TLC Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCIe NVMe Gen4X4 Performance Minimum Sequential Read Minimum Sequential Write 6400 MB/s ±20% 5000 MB/s ±20% Logical Blocks 2,00,049,264 Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features Pyrite 2.0; TRIM; L1.2 NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 11) is reserved for system recovery software. SSD 2TB 2280 PCIe-4x4 Form Factor M.2 2280 NVMe Three Layer Cell Form Factor M.2 2280 Vieth 0.09 in (2.3 mm) Uidth Width 0.87 in (22 mm) UC Height 0.02 lb (10 g) UID (10 g) Interface PCIe NVMe Gen4X4 UID (10 g) Weight 0.02 lb (10 g) UID (10 g) Interface PCIe NVMe Gen4X4 UID (10 g) Performance Minimum Sequential Read Minimum Sequential Write MOUD (10 g) UID (10 g) <th></th> <th>Form Factor</th> <th>M.2 2280</th> <th></th>		Form Factor	M.2 2280		
Note the set of the	NVMe Three Layer Cell	Capacity	1TB		
 width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCIe NVMe Gen4X4 Performance Minimum Sequential Read 6400 MB/s ±20% Cogical Blocks 2,000,409,264 Operating Temperature 2° to 158°F (0° to 70°C) [amistree degrading degrading		NAND Type	TLC		
Weight Interface0.02 b(0.0)Jennum Sequential Que PerformanceMinimum Sequential Read 400 MDS ± 200%Minimum Sequential Que 500 MDS ± 200%Logical Blocks Operating Temperature3.004,092.64		Height	0.09 in (2.3 mm)		
Interface PCIe NVMe Gen4X4 Performance Minimum Sequential Read Minimum Sequential Write 6400 MB/s ±20% 5000 MB/s ±20% Logical Blocks 2,000,409,264 Operating Temperature 2° to 158°F (0° to 70°C) [ambut temp] Features Pyrite 2.0; TRIM; L1.2 NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 11) is reserved for system recovery software. SSD 2TB 2280 PCIe-4x4 Form Factor M.2 2280 NNMe Three Layer Cell Form Factor M.2 2280 Rapidty 2TB TB NAND Type TLC Height NAND Type 0.09 in (2.3 mm) Uidth Width 0.87 in (22 mm) Uidth Width 0.92 lb (10 g) Interface Interface PCIe NVMe Gen4X4 Form Sequential Read Performance Minimum Sequential Read Minimum Sequential Write 6400 MB/s ±20% 5000 MB/s ±20% 5000 MB/s ±20% Logical Blocks 6400 MB/s ±20% 5000 MB/s ±20% Logical Blocks 62° to 158°F (0° to 70°C) [ambut temp]		Width	0.87 in (22 mm)		
Performance Minimum Sequential Read Minimum Sequential Write 6400 MB/s ±20% 5000 MB/s ±20% Logical Blocks 2,000,409,264 Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features Pyrite 2.0; TRIM; L1.2 NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 11) is reserved for system recovery software. SSD 2TB 2280 PCIe-4x4 Form Factor M.2 2280 Capacity 2TB		Weight	0.02 lb (10 g)		
6400 MB/s ±20% 5000 MB/s ±20% Logical Blocks 2,000,409,264 Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Pyrite 2.0; TRIM; L1.2 Pyrite 2.0; TRIM; L1.2 NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 11) is reserved for system recovery software. SSD 2TB 2280 PCle-4x4 Form Factor NVMe Three Layer Cell Form Factor MAND Type 2TB NAND Type TLC Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCle NVMe Gen4X4 Performance Minimum Sequential Read Minimum Sequential Write 6400 MB/s ±20% 5000 MB/s ±20% 5000 MB/s ±20%		Interface	PCIe NVMe Gen4X4		
Logical Blocks Operating Temperature Features2,000,409,264 32° to 158°F (0° to 70°C) [ambi=nt temp]Pyrite 2.0; TRIM; L1.2 NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual armatted capacity is less. Up to 35 GB (for Windows 11) is reserved for system recovery software.SSD 2TB 2280 PCIe-444 NVMe Three Layer CellForm FactorM.2 2280AmnD TypeM.2 22802TBMAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen4X4PerformanceMinimun Sequential Real 6400 MB/s ±20%Logical Blocks4.000,797,360Uperating Temperature32° to 158°F (0° to 70°C) [ambi-stremp]		Performance	Minimum Sequential Read	Minimum Sequential Write	
Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features Pyrite 2.0; TRIM; L1.2 NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 11) is reserved for system recovery software. SSD 2TB 2280 PCIe-444 Form Factor M.2 2280 NVMe Three Layer Cell Form Factor M.2 2280 Capacity 2TB ZTB NAND Type TLC Height N07 in (22 mm) Uithin 0.87 in (22 mm) Width 0.87 in (22 mm) Uithin 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface Performance Minimum Sequential Read Minimum Sequential Write 6400 MB/s ±20% 5000 MB/s ±20% 5000 MB/s ±20%			6400 MB/s ±20%	5000 MB/s ±20%	
Features Pyrite 2.0; TRIM; L1.2 NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 11) is reserved for system recovery software. SSD 2TB 2280 PCle-4x4 Form Factor M.2 2280 NVMe Three Layer Cell Form Factor M.2 2280 NAND Type TLC Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCle NVMe Gen4X4 Performance Minimum Sequential Read Minimum Sequential Write 6400 MB/s ±20% 5000 MB/s ±20% 5000 MB/s ±20% Logical Blocks 0,20,797,360 32° to 158°F (0° to 70°C) [ambit temp]		Logical Blocks	2,000,409,264		
SSD 2TB 2280 PCIe-4x4 Form Factor M.2 2280 NVMe Three Layer Cell Form Factor M.2 2280 NAND Type TLC TLC Height 0.09 in (2.3 mm) Width Width 0.87 in (22 mm) Width Weight 0.02 lb (10 g) Interface Performance Minimum Sequential Read Minimum Sequential Write 6400 MB/s ±20% 5000 MB/s ±20% 5000 MB/s ±20% Logical Blocks 4,000,797,360 2° to 158°F (0° to 70°C) [ambi=nt temp]		Operating Temperature	32° to 158°F (0° to 70°C) [amb	vient temp]	
formatted capacity is less. Up to 35 GB (for Windows 11) is reserved for system recovery software.SSD 2TB 2280 PCle-4x4 NVMe Three Layer CellForm FactorM.2 2280Capacity2TBCapacityTLCNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen4X4PerformanceMinimum Sequential ReadMinimum Sequential Write6400 MB/s ±20%5000 MB/s ±20%5000 MB/s ±20%Logical Blocks0,00,797,36032° to 158°F(0° to 70°C) [artterp]		Features	Pyrite 2.0; TRIM; L1.2		
NVMe Three Layer Cell Capacity 2TB NAND Type TLC Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCle NVMe Gen4X4 Performance Minimum Sequential Read Minimum Sequential Write 6400 MB/s ±20% 5000 MB/s ±20% Logical Blocks 4,000,797,360 5000 MB/s ±20%			formatted capacity is less. Up		
NAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen4X4PerformanceMinimum Sequential ReadMinimum Sequential Write6400 MB/s ±20%5000 MB/s ±20%Logical Blocks4,000,797,360Operating Temperature32° to 158°F (0° to 70°C) [ambitument)		Form Factor	M.2 2280		
Height0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen4X4PerformanceMinimum Sequential ReadMinimum Sequential Write6400 MB/s ±20%5000 MB/s ±20%Logical Blocks4,000,797,360Operating Temperature32° to 158°F (0° to 70°C) [arriter temp]	NVMe Three Layer Cell	Capacity	2TB		
Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen4X4PerformanceMinimum Sequential ReadMinimum Sequential WriteLogical Blocks4,000,797,3605000 MB/s ±20%Operating Temperature32° to 158°F (0° to 70°C) [arr temp]		NAND Type	TLC		
Weight0.02 lb (10 g)InterfacePCle NVMe Gen4X4PerformanceMinimum Sequential ReadMinimum Sequential Write6400 MB/s ±20%5000 MB/s ±20%Logical Blocks4,000,797,360Operating Temperature32° to 158°F (0° to 70°C) [amb temp]		Height	0.09 in (2.3 mm)		
InterfacePCle NVMe Gen4X4PerformanceMinimum Sequential ReadMinimum Sequential Write6400 MB/s ±20%5000 MB/s ±20%Logical Blocks4,000,797,360Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Width	0.87 in (22 mm)		
PerformanceMinimum Sequential Read 6400 MB/s ±20%Minimum Sequential Write 5000 MB/s ±20%Logical Blocks4,000,797,360Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Weight	0.02 lb (10 g)		
6400 MB/s ±20% 5000 MB/s ±20% Logical Blocks 4,000,797,360 Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]		Interface	PCIe NVMe Gen4X4		
Logical Blocks4,000,797,360Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Performance	Minimum Sequential Read	Minimum Sequential Write	
Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]			6400 MB/s ±20%	5000 MB/s ±20%	
		Logical Blocks	4,000,797,360		
Features Pyrite 2.0; TRIM; L1.2		Operating Temperature	32° to 158°F (0° to 70°C) [amb	vient temp]	
		Features	Pyrite 2.0; TRIM; L1.2		





Technical Specifications – Storage

			= 1 billion bytes. TB = 1 trillion bytes. Actual	
		system recovery software.	to 35 GB (for Windows 11) is reserved for	
256GB PCIe 2280 NVMe	Form Factor	M.2 2280		
Self Encrypted OPAL2	Capacity	256GB		
Value Solid State Drive	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Weight	0.02 lb (10 g)		
	Interface	PCIe NVMe Gen4X4		
	Performance	Minimum Sequential Read	Minimum Sequential Write	
		2000 MB/s ±20%	900 MB/s ±20%	
	Logical Blocks	500,118,192		
	Operating Temperature	32° to 158°F (0° to 70°C) [amb	ient temp]	
	Features	TCG Opal 2.0; TRIM; L1.2		
			= 1 billion bytes. TB = 1 trillion bytes. Actual to 35 GB (for Windows 11) is reserved for	
512GB PCIe-4x4 2280	Form Factor	M.2 2280		
NVME Self Encrypted	Capacity	512GB		
OPAL2 Three Layer Cell Solid State Drive	NAND Type	TLC		
Joliu Jlale DIIVe	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Weight	0.02 lb (10 g)		
	Interface	PCIe NVMe Gen4X4		
	Performance	Minimum Sequential Read	Minimum Sequential Write	
		6400 MB/s ±20%	3500 MB/s ±20%	
	Logical Blocks	1,000,215,215		
	Operating Temperature	32° to 158°F (0° to 70°C) [amb	ient temp]	
	Features	TCG Opal 2.0; TRIM; L1.2		
			= 1 billion bytes. TB = 1 trillion bytes. Actual to 35 GB (for Windows 11) is reserved for	
SSD 1TB 2280 PCIe NVMe	Form Factor	M.2 2280		
Value	Capacity	1TB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Weight	0.02 lb (10 g)		
	Interface	PCIe NVMe Gen4X4		
	Performance	Minimum Sequential Read 2200 MB/s ±20%	Minimum Sequential Write 1600 MB/s ±20%	
	Logical Blocks	2,000,409,264		
	Operating Temperature	32° to 158°F (0° to 70°C) [amb	ient temp]	
	Features	Pyrite 2.0; TRIM; L1.2	iene cempj	
		· Juce 2.0, 1100, 21.2		





Technical Specifications – Storage

			= 1 billion bytes. TB = 1 trillion bytes. Actual to 35 GB (for Windows 11) is reserved for
SSD 256GB 2280 PCIe	Form Factor	M.2 2280	
NVMe Value	Capacity	256 GB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (10 g)	
	Interface	PCIe NVMe Gen4X4	
	Performance	Minimum Sequential Read	Minimum Sequential Write
		2000 MB/s ±20%	900 MB/s ±20%
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [amb	pient temp]
	Features	Pyrite 2.0; TRIM; L1.2	
			= 1 billion bytes. TB = 1 trillion bytes. Actual to 35 GB (for Windows 11) is reserved for
SSD 512GB 2280 PCIe	Form Factor	M.2 2280	
NVMe Value	Capacity	512 GB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (10 g)	
	Interface	PCIe NVMe Gen4X4	
	Performance	Minimum Sequential Read	Minimum Sequential Write
		2200 MB/s ±20%	1000 MB/s ±20%
	Logical Blocks	1,000,215,215	
	Operating Temperature	32° to 158°F (0° to 70°C) [amb	pient temp]
	Features	Pyrite 2.0; TRIM; L1.2	
			= 1 billion bytes. TB = 1 trillion bytes. Actual to 35 GB (for Windows 11) is reserved for



Technical Specifications – Networking

NETWORKING/COMMUNICATION

Intel® AX211 Wi-Fi 6E +Bluetooth® 5.3 wireless card M.2 160MHz CNVi World-wide WLAN vPro® 1		IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi certified
	Frequency Band	802.11b/g/n/ax • 2.402 - 2.482 GHz 802.11a/n/ac/ax • 4.9 - 4.95 GHz (Japan) • 5.15 - 5.25 GHz • 5.25 - 5.35 GHz • 5.47 - 5.725 GHz • 5.825 - 5.850 GHz • 5.955 - 6.415 GHz • 6.435 - 6.515 GHz • 6.535 - 6.875 GHz • 6.895 - 7.115 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 300Mbps 802.11ac : 1733Mbps 802.11ax : max 2.4Gbps
	Modulation	Direct Sequence Spread Spectrum
		OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM
	Security ¹	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification IEEE 802.11i WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer)
		Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points



Technical Specifications – Networking

Output Power² • 802.11b : +17dBm minimum • 802.11a : +16dBm minimum • 802.11a : +17dBm minimum • 802.11n HT20(2.4GHz) : +14dBm minimum • 802.11n HT40(2.4GHz) : +13dBm minimum • 802.11n HT20(5GHz) : +14dBm minimum • 802.11n HT40(5GHz) : +13dBm minimum • 802.11ac VHT80(5GHz) : +10dBm minimum 802.11ac VHT160(5GHz): +10dBm minimum 802.11ax HE40(2.4GHz): +12dBm minimum 802.11ax HE80(5GHz) : +10dBm minimum • 802.11ax HE160(5GHz) : +10dBm minimum **Power Consumption** Transmit mode 2.0 W Receive mode 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated) Connected Standby 10mW Radio disabled 8 mW **Power Management** ACPI and PCI Express compliant power management 802.11 compliant power saving mode **Receiver Sensitivity³** •802.11b, 1Mbps : -93.5dBm maximum •802.11b, 11Mbps : -84dBm maximum • 802.11a/g, 6Mbps : -86dBm maximum • 802.11a/q, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum • 802.11n, MCS15 : -64dBm maximum • 802.11ac, MCS0(VHT80) : -84dBm maximum • 802.11ac, MCS9(VHT80) : -59dBm maximum 802.11ac, MCS9(VHT160): -58.5dBm maximum •802.11ax, MCS11(HE40): -57dBm maximum •802.11ax. MCS11(HE80): -54dBm maximum •802.11ax, MCS11(HE160): -53.5dBm maximum High efficiency antenna with spatial diversity, mounted in the Antenna Type display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications **Form Factor** PCI-Express M.2 MiniCard Dimensions 1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm Weight 1. Type 2230 : 2.8q 2. Type 1216: 1.3g **Operating Voltage** 3.3v +/- 9% Temperature Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C) Humidity Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing) Altitude Operating Non-0 to 10,000 ft (3,048 m) operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber – Radio Off; LED Off – Radio ON

Technical Specifications – Networking

Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbp voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR an EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management	ETS 300 328, ETS 300 826
Certifications	Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	Bluetooth® 4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan Bluetooth® 4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) Bluetooth®- 5.2 ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range Bluetooth® 5.3 Host to Controller Encryption Key Control Enahancements Compliance to the latest Errata Sectipn 12.3 of Bluetooth® 5.3 wireless card specification



Technical Specifications – Networking

1. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported. Wi-Fi 6E is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

2. Check latest software/driver release for updates on supported security features.

3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

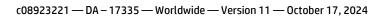
4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Intel® AX211 Wi-Fi 6E + Bluetooth® 5.3 wireless card M.2 160MHz CNVi World-wide WLAN nonvPro ® Wireless Card1	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11ac IEEE 802.11ac IEEE 802.11d IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11v
	Interoperability Frequency Band	Wi-Fi certified 802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz • 5.955 – 6.415 GHz • 6.435 – 6.515 GHz • 6.535 – 6.875 GHz • 6.895 – 7.115 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 300Mbps 802.11ac: 1733Mbps 802.11ax: max 2.4Gbps
	Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM
	Security ¹	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.



Technical Specifications – Networking

	 WPA2 certification WPA3 certification IEEE 802.11i WAPI
Network Architecture Models	Ad-hoc (Peer to Peer)
	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ²	 802.11b : +17dBm minimum 802.11g : +16dBm minimum 802.11a : +17dBm minimum 802.11n HT20(2.4GHz) : +14dBm minimum 802.11n HT40(2.4GHz) : +13dBm minimum 802.11n HT20(5GHz) : +14dBm minimum 802.11n HT40(5GHz) : +13dBm minimum 802.11ac VHT80(5GHz) : +10dBm minimum 802.11ax HE40(2.4GHz) : +12dBm minimum 802.11ax HE80(5GHz) : +10dBm minimum 802.11ax HE160(5GHz) : +10dBm minimum
Power Consumption	 Transmit mode 2.0 W Receive mode 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated) Connected Standby 10mW Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity ³ Antenna Type	 802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0(VHT80) : -84dBm maximum 802.11ac, MCS9(VHT80) : -59dBm maximum 802.11ac, MCS9(VHT60) : -58.5dBm maximum 802.11ax, MCS11(HE40): -57dBm maximum 802.11ax, MCS11(HE80): -54dBm maximum 802.11ax, MCS11(HE60): -53.5dBm maximum 802.11ax, MCS11(HE160): -53.5dBm maximum
	display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230 : 2.8g 2. Type 1216: 1.3g
Operating Voltage	3.3v +/- 9%





Technical Specifications – Networking

5			
Temperature	Operating Non-operating	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)	
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating Non- operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OF	FF; LED White – Radio ON	
HP Integrated Module with Bluet	ooth 4.0/4.1/4.2/5.0/5	.1/5.2/5.3 Wireless Technology	
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy : 0~79 (1 MHz/ BLE : 0~39 (2 MHz/CH		
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
Transmit Power		nent shall operate as a Class II Bluetooth m transmit power of + 9.5 dBm for BR and	
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17	' mW	
Bluetooth Software Supported Link Topology	Microsoft Windows Bl	uetooth Software	
Power Management	Microsoft Windows AC	PI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark		
Bluetooth Profiles Supported	Bluetooth [®] 4.1-ESR 5 LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Dir LE L2CAP Connection Train Nudging & Inter Bluetooth [®] 4.2 ESR08 LE Secure Connection LE Privacy 1.2 –Link L LE Privacy 1.2 –Exten LE Data Packet Lengtl FAX Profile (FAX) Basic Imaging Profile Headset Profile (HSP) Hands Free Profile (HI Advanced Audio Distri Bluetooth [®] 5.2	ected Advertising Oriented Channels laced Scan Compliance - Basic/Full ayer Privacy ded Scanner Filter Policies n Extension (BIP)2 FP)	



Technical Specifications – Networking

ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range Bluetooth® 5.3 Host to Controller Encryption Key Control Enahancements Compliance to the latest Errata Sectipn 12.3 of Bluetooth® 5.3 wireless card specification

1. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported. Wi-Fi 6E is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

2. Check latest software/driver release for updates on supported security features.

3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP 5G Sub-6 Cat 19 WWAN eSIM

WCDMA/HSPA+ operating bands:
Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL)
Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL)
Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL)
Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL)
Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL)
LTE FDD/TDD operating bands:
Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL)
Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL)
Band 3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL)
Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL)
Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL)
Band 7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL)
Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL)
Band 12: 699 to 716 MHz (UL), 729 to 746 MHz (DL)
Band 13: 777 to 787 MHz (UL), 746 to 756 MHz (DL)
Band 14: 788 to 798 MHz (UL), 758 to 768 MHz (DL)
Band 17: 704 to 716 MHz (UL), 734 to 746 MHz (DL)
Band 18: 815 to 830 MHz (UL), 860 to 875 MHz (DL)
Band 19: 830 to 845 MHz (UL), 875 to 890 MHz (DL)
Band 20: 832 to 862 MHz (UL), 791 to 821 MHz (DL)
Band 25: 1850 to 1915 MHz (UL), 1930 to 1995 MHz (DL)
Band 26: 814 to 849 MHz (UL), 859 to 894 MHz (DL)
Band 28: 703 to 748 MHz (UL), 758 to 803 MHz (DL)
Band 29: 717 to 728 MHz (DL)
Band 30: 2305 to 2315 MHz (UL) 2350 to 2360 MHz (DL)
Band 32: 1452 to 1496 MHz (DL)
Band 34: 2010 to 2025 MHz (UL/DL)
Band 38: 2570 to 2620 MHz (UL/DL)
Band 39: 1880 to 1920 MHz (UL/DL)



Technical Specifications – Networking

	Band 40: 2300 to 2400 MHz (UL/DL) Band 41: 2496 to 2690 MHz (UL/DL) Band 42: 3400 to 3600 MHZ (UL/DL) Band 43: 3400 to 3800 MHZ (UL/DL) Band 46: 5150 to 5925 MHZ (DL) Band 46: 5150 to 5925 MHZ (DL) Band 48: 3550 to 3700 MHZ (UL), 2110 to 2200 MHz (DL) Band 71: 663 to 698 MHz (UL), 2110 to 2200 MHz (DL) Band 71: 663 to 698 MHz (UL), 2110 to 2170 MHz (DL) n2: 1850 to 1910 MHz (UL), 2110 to 2170 MHz (DL) n3: 1710 to 1785 MHz (UL), 1930 to 1990 MHz (DL) n3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL) n5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) n7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL) n8: 880 to 915 MHz (UL), 791 to 821 MHz (DL) n25: 1850 to 1915 MHz (UL), 1930 to 1995 MHz (DL) n26: 832 to 862 MHz (UL), 758 to 803 MHz (DL) n30: 2305 to 2315 MHz (UL), 2350 to 2360 MHz (DL) n38: 2570 to 2620 MHz (UL/DL) n40: 2300 to 2400 MHz (UL/DL) n41: 2496 to 2690 MHz (UL/DL) n71: 663 to 698 MHz (UL), 617 to 652 MHz (DL) n71: 663 to 698 MHz (UL), 101 n77: 3300 to 4200 MHz (UL/DL) n77: 3300 to 4200 MHz (UL/DL) n77: 3300 to 4200 MHz (UL/DL)
Wireless protocol standards	NR Sub6G rel15 200MHz 2 DLCA, 256 QAM 200MHz 2 ULCA, 256 QAM 15KHz/30KHz SCS for FDD/TDD LTE Rel15 100MHz 5 DLCA, 256 QAM 40MHz 2 ULCA, 256 QAM UMTS Rel8
GPS GPS bands	GPS only support L1 C/A GPS: L1 (1575.42MHz) GLONASS: L1 (1602MHz) BeidouB1(1561.098MHz) Galileo E1 (1575.42) QZSS(1575.42 MHz)
Maximum data rates	Sub-6 SA Peak DL 4.67Gbps/UL 1.25Gbps Sub-6 NSA Peak DL 3.74Gbps/UL 835Mbps LTE Peak DL 1.6Gbps (CAT19)/UL 211Mbps (CAT18) UMTS/HSPA+ DL DC-HSPA+: 42 Mbps (CAT24)/UL 11.5 Mbps (CAT7)
Maximum output power	NR: 23 dBm in all band except (n30 = 22dBm & n48=21dBm & n77=25dBm & n41/n77/n78 = 26dBm) LTE:



Technical Specifications – Networking

	23 dBm in all band except (B30 = 22dBm & B48=21dBm & B41=26dBm) UMTS: 23.5 dBm			
Maximum power consumption	3500 mA (peak); 1674mA (average)			
Form Factor	M.2, 3042-S3 Key B			
Weight	8.7g			
Dimensions (Length x Width x Thickness)	52 mm × 30 mm × 2.3 mm			

embedded eSIM

Support

*5G module is optional and must be configured at the factory. Module designed for 5G NR NSA (non-standalone) networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP. Module requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Data connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select platforms and select countries, where carrier supported.

HP 4G LTE-A Pro Cat16 WWAN eSIM

Technology/Operating bands*	WCDMA/HSPA+ operating bands: Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL) Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) LTE FDD/TDD operating bands: Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) Band 3: 1710 to 1785 MHz (UL), 1930 to 1990 MHz (DL) Band 3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL) Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL) Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) Band 7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL) Band 8: 880 to 915 MHz (UL), 729 to 746 MHz (DL) Band 12: 699 to 716 MHz (UL), 729 to 746 MHz (DL) Band 13: 777 to 787 MHz (UL), 746 to 756 MHz (DL) Band 14: 788 to 798 MHz (UL), 734 to 746 MHz (DL) Band 17: 704 to 716 MHz (UL), 860 to 875 MHz (DL) Band 18: 815 to 830 MHz (UL), 875 to 890 MHz (DL) Band 20: 832 to 862 MHz (UL), 875 to 890 MHz (DL) Band 20: 832 to 862 MHz (UL), 791 to 821 MHz (DL) Band 20: 832 to 862 MHz (UL), 758 to 768 MHz (DL) Band 20: 832 to 862 MHz (UL), 758 to 803 MHz (DL) Band 20: 832 to 862 MHz (UL), 859 to 894 MHz (DL) Band 20: 814 to 849 MHz (UL), 758 to 803 MHz (DL) Band 26: 814 to 849 MHz (UL), 758 to 803 MHz (DL) Band 29: 717 to 728 MHz (DL) Band 30: 2305 to 2315 MHz (UL) 2350 to 2360 MHz (DL) Band 32: 1452 to 1496 MHz (DL) Band 34: 2010 to 2025 MHz (UL)D)
	Band 32: 1452 to 1496 MHz (DL)



Technical Specifications – Networking

Wireless protocol standards	Band 41: 2496 to 2690 MHz (UL/DL) Band 42: 3400 to 3600 MHZ (UL/DL) Band 43: 3400 to 3800 MHZ (UL/DL) Band 48: 3550 to 3700 MHZ (UL/DL) Band 66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL) Band 71: 663 to 698 MHz (UL), 617 to 652 MHz (DL) 3GPP LTE Rel15 LTE Specification, 100MHz 5 DLCA, 256 QAM, DL 1.0Gbps (CAT16)/ 40MHz 2 ULCA, 256 QAM, UL 211Mbps (CAT18) WCDMA 3GPP Release 8 UMTS Specification, DL UMTS: 384 kbps/UL 384 kbp, DL DC-HSPA+: 42 Mbps (CAT24)/UL 11.5 Mbps (CAT7) WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification			
GPS	Standalone, A-GPS (MS-A, MS-B)			
GPS Bands	GPS: L1 (1575.42MHz) GLONASS: L1 (1602MHz) BeidouB1(1561.098MHz) Galileo E1 (1575.42) QZSS(1575.42 MHz)			
Maximum Data Rates	LTE: ue-CategoryDL 16, (DL : 1 Gbps) ue-CategoryUL 18 , (UL: 211Mbps) DC-HSPA+: 42 Mbps (Download), 11.5 Mbps (Upload)			
Maximum Output Power	 r HPUE: Not supported LTE: 23 dBm in all band except (B30= 22dBm& B48= 21dBm) UMTS: 23.5 dBm 			
Maximum Power Consumption	LTE: 1300 mA (peak); 1100 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)			
Form Factor	М.2, 3052-S3 Кеу В			
Weight	8 g			
Dimensions (Length x Width x Thickness)	52 mm × 30 mm × 2.3 mm			
eSIM	Support			

*Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

NFC NXP NPC300

Dimensions (L x W					
x H)	17 x 10 x 2.0 mm				
Chipset	NPC300				
System interface	12C				
NFC RF standards	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2				
NFC Forum Support	Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2				



Technical Specifications – Networking

	Reader (PCD-VCD) Mode(1)	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards				
	Card Emulation (PICC- VICC) Mode(1)					
	Frequency	13.56 MHz				
	NFC Modes Supported Reader/Writer, Pee			er-to-Peer		
	Raw RF Data Rates	106, 212, 424, 848 kbps				
	Operating temperature					
	Storage temperature	0°C to 70°C rature -20°C to 125°C				
	Humidity	10-90% operating 5-95% non-operati				
	Supply Operating voltage 4.35 to 5.25 Volts					
	I/O Voltage	1.8V or 3.3V				
	Power Consumption	Booster enable,	VBAT= 3.3V,			
		VCC_BOOST = 5V)	Polling	7.3 mA		
		Mode Power Consumption,	Detected Test Tag Type 1	Total 283.8 mA Net Module 236.8 mA		
		Typical	Detected Test Tag Type 2	Total 288.8 mA Net Module 241.8 mA		
			Detected Test Tag Type 3	Total 287.7 mA Net Module 240.7 mA		
			Detected Test Tag Type 4	Total 282.3 mA Net Module 235.3 mA		
	Antenna	Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is external to module.				
Qualcomm [®] 9205						
Technology/Operating bands*	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 14 upper), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1900 (Band 25), 850 (Band 26), 800 (Band 27), 700 (Band 28), 1700/2100 (Band 66), 700 (band 85) MHz. GSM/GPRS/EGPRS: 850, 900, 1800, 1900MHz.					
Wireless protocol standards	 3GPP TS 51.010-1 V10.5.0: Mobile Station (MS) conformance specification; Part 1: Conformance specification 3GPP TS 36.521-1 V14.3.0: User Equipment (UE) conformance specification; Radio transmission and reception; Part 1: Conformance testing 3GPP TS 21.111 V10.0.0: USIM and IC card requirements 3GPP TS 51.011 V4.15.0: Specification of the Subscriber Identity Module -Mobile Equipment (SIM-ME) interface 3GPP TS 31.102 V10.11.0: Characteristics of the Universal Subscriber 					



Identity Module (USIM) application • 3GPP TS 31.11 V10.16.0: Universal Subscriber Identity Module (USIM) Application Toolkit (USAT) • 3GPP TS 36.124 V10.3.0: Electro Magnetic Compatibility (EMC) requirements for mobile terminals and ancillary equipment • 3GPP TS 27.007 V10.0.8: AT command set for User Equipment (UE) • 3GPP TS 27.005 V10.0.1: Use of Data Terminal Equipment - Data Circuit terminating Equipment (DTE - DCE) interface for Short Message Service (SMS) and Cell Broadcast Service (CBS)
Standalone GPS/Beidou/Glonass, A-GPS (MS-A, MS-B)
1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz
LTE FDD: 375 Kbps (Download), 1119 Kbps (Upload) GSM: - GPRS: 107 Kbps (Download), 85.6 Kbps (Upload) - EGPRS: 296 Kbps (Download), 236.8 Kbps (Upload)
LTE: 21.5 dBm in all band GSM:34dBm
LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
M.2, 2242-S3 Key B
5.5 g
22 x 42 x 2.3 mm
Support

11. LPWAN (also called Mobile Narrowband) does not support mobile broadband use.

AUDIO

HD Stereo Codec Audio I/O Ports	Realtek ALC3315 Headset: CTIA only and Headphone-out
Internal Speaker Amplifier	Cirrus Logic High-Efficiency Boosted Class D Amplifier
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio. Following MSFT Behaviour
Sampling	DAC:48kHz ADC:48kHz
Wavetable Syntheses	N/A
Analog Audio	Support 3.5mm Headset: CTIA only and Headphone-out
# of Channels on Line- Out	N/A
Internal Speaker	Yes

FINGERPRINT READER



Sensor vendor	Synaptics
Sensor type	Capacitive
DPI resolution	363 DPI
Scan area	104 x 86 pixels
False Rejection Rate	FRR=≤ 3%
False Acceptance Rate	FAR 1/100K
Mobile Voltage Operation	n 3.0V to 3.6V
Operating Temperature	0~60C
Current Consumption Image	100mA max
Low Latency Wait For Finger	260uA
Capture Rate	50 Frames/ sec
ESD Resistance	IEC 61000-4-2 4B (+15KV)
Detection Matrix	363 dpi / 7.4x6mm sensor area
Sensor vendor	Flan
Sensor vendor Sensor type	Elan Capacitive
Sensor vendor Sensor type DPI resolution	Capacitive
Sensor type	Capacitive 508 DPI
Sensor type DPI resolution Scan area	Capacitive
Sensor type DPI resolution Scan area False Rejection Rate	Capacitive 508 DPI 80 x 80 pixels
Sensor type DPI resolution Scan area	Capacitive 508 DPI 80 x 80 pixels FRR=≤ 3% FAR 1/100K
Sensor type DPI resolution Scan area False Rejection Rate False Acceptance Rate	Capacitive 508 DPI 80 x 80 pixels FRR=≤ 3% FAR 1/100K
Sensor type DPI resolution Scan area False Rejection Rate False Acceptance Rate Mobile Voltage Operation	Capacitive 508 DPI 80 x 80 pixels FRR=≤ 3% FAR 1/100K n 2.7V to 3.6V
Sensor type DPI resolution Scan area False Rejection Rate False Acceptance Rate Mobile Voltage Operation Operating Temperature Current Consumption	Capacitive 508 DPI 80 x 80 pixels FRR=≤ 3% FAR 1/100K n 2.7V to 3.6V -20~80C
Sensor type DPI resolution Scan area False Rejection Rate False Acceptance Rate Mobile Voltage Operation Operating Temperature Current Consumption Image Low Latency Wait For	Capacitive 508 DPI 80 x 80 pixels FRR=≤ 3% FAR 1/100K n 2.7V to 3.6V -20~80C 35mA max
Sensor type DPI resolution Scan area False Rejection Rate False Acceptance Rate Mobile Voltage Operation Operating Temperature Current Consumption Image Low Latency Wait For Finger	Capacitive 508 DPI 80 x 80 pixels FRR=≤ 3% FAR 1/100K n 2.7V to 3.6V -20~80C 35mA max 300uA
Sensor type DPI resolution Scan area False Rejection Rate False Acceptance Rate Mobile Voltage Operation Operating Temperature Current Consumption Image Low Latency Wait For Finger Capture Rate	Capacitive 508 DPI 80 x 80 pixels FRR=≤ 3% FAR 1/100K a 2.7V to 3.6V -20~80C 35mA max 300uA 50 Frames/ sec

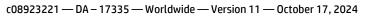
POWER

Straight 1.8m	Dimensions Weight	3.543 x 2.008 x 1.122 in (9.0x5.1x2.85cm) 240g ± 10g		
	Input	Input Efficiency	81.50% min at 115 Vac/ 230 Vac @5.00V 86.70% min at 115 Vac/ 230 Vac @9.00V 88.00% min at 115 Vac/ 230 Vac @12.00V 89.00% min at 115 Vac/ 230 Vac @15.00V 89.00% min at 115 Vac/ 230 Vac @20.00V	
		Input frequency range	47 ~ 63 Hz	
		Input AC current	Max. 1.6 A at 90 Vac	
	Output	Output power	5V/15W 9V/27W 12V/60W 15V/65W	



Technical Specifications – Networking

			20V/65W
		DC output	5V/9V/12V/15V/20V
		Hold-up time	100% load 5ms at 115 Vac input
		Output current limit	<8.0A
		AC Inlet Type	C6
		DC Cable Connector	USB type C
		DC Cable Material	PVC
	Connector	C6	
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	Worldwide safety standar EN62368-1:2014+A11, UL Agency approvals - C-UL-I B, CISPR32 Class B, CCC an	JS, TUV/GS, TUV/PSE, EN55032 Class B, FCC Class Id CECP, CU(EAC), EAEU, KCC(Safety+EMC) and K- NYCE, NRcan, NRCS, ISC, SEC, PSB, Argentina S-
HP 65W Slim USB-C	Dimensions	3.819 x 2.106 x 0.827 in (9.7x5.35x2.1cm)
Straight AC Power Adapter	Weight	220g ±10g	
nuuptei	Input	Input Efficiency	81.50% min at 115 Vac/ 230 Vac @5.00V 86.70% min at 115 Vac/ 230 Vac @9.00V 88.00% min at 115 Vac/ 230 Vac @12.00V 89.00% min at 115 Vac/ 230 Vac @15.00V 89.00% min at 115 Vac/ 230 Vac @20.00V
		Input frequency range	47-63Hz
		Input AC current	Max. 1.6 A at 90 Vac
	Output	Output power	5V/15W 9V/27W 12V/60W 15V/65W 20V/65W
		DC output	5V/9V/12V/15V/20V
		Hold-up time	100% load 5ms at 115 Vac input
		Output current limit	< 8.0A
		AC Inlet Type	C6
		DC Cable Connector	USB type C
		DC Cable Material	PVC
	Connector	C6	
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)



		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	FMI and Cafatu		with LVD and EMC directives
	EMI and Safety Certifications	Worldwide safety standar EN62368-1:2014+A11, UL Agency approvals - C-UL-I B, CISPR32 Class B, CCC an	ds - IEC60950-1 and IEC62368-1 : 2018, - 62368-1 US, TUV/GS, TUV/PSE, EN55032 Class B, FCC Class Id CECP, CU(EAC), EAEU, KCC(Safety+EMC) and K- NYCE, NRcan, NRCS, ISC, SEC, PSB, Argentina S-
HP 100W Slim USB-C	Dimensions	5.354 x 2.362 x 0.866 in (*	13.6x6.0x2.2cm)
Straight AC Power Adapter	Weight	380g ±10g	
παρτει	Input	Input Efficiency	81.50% min at 115 Vac/ 230 Vac @5.00V 86.70% min at 115 Vac/ 230 Vac @9.00V 88.00% min at 115 Vac/ 230 Vac @12.00V 89.00% min at 115 Vac/ 230 Vac @15.00V 89.00% min at 115 Vac/ 230 Vac @20.00V
		Input frequency range	47-63Hz
		Input AC current	Max. 1.6 A at 90 Vac
	Output	Output power	5V/15W 9V/27W 12V/60W 15V/75W 20V/100W
		DC output	5V/9V/12V/15V/20V
		Hold-up time	100% load 5ms at 115 Vac input/80% load 10ms at 115 Vac input
		Output current limit	5V/9V/12V/15V<125% max current, 20V<135% max current
		AC Inlet Type	C6
		DC Cable Connector	USB type C
		DC Cable Material	PVC
	Connector	C6	
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	Worldwide safety standar IEC62368-1 : 2018, EN623 Agency approvals - C-UL-I B, CISPR32 Class B, CCC, C	with LVD and EMC directives ds - IEC60950-1, IEC 62368-1:2014 and 368-1:2020+A11, UL 62368-1 US, TUV/GS, TUV/PSE, EN55032 Class B, FCC Class U(EAC), KCC(Safety+EMC), NOM-001 NYCE, NRcan, ntina S-mark, Australia RCM, BIS, BSMI, UAE, UKCA oHS+ECO)

HP 3-cell Long Life Li-Ion	Dimensions (H x W x L)	251.8*70.3*6.82mm (9.91*2.77*0.27 inch)		
(56 WHr)	Weight	0.205kg +/- 10g(0.474 lb)		
	Cells/Type	3cell Lithium-Ion Polymer	cell / 586075	
	Energy	Voltage	11.58V	
		Amp-hour capacity	4.84Ah	
		Watt-hour capacity	56.04Wh	
	Temperature	Operating (Charging)	32° to 113° F (0° to 45° C)	
		Operating (Discharging)	14° to 140° F (-10° to 60° C)	
	Fuel Gauge LED	NA		
	Warranty	Follow product spec		
	Optional Travel Battery Available	No		
	decrease with shelf life, tir		capacity. Battery capacity will naturally nperature, system configuration, loaded apps, ors.	

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations	 This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR[®] US Federal Energy Management Program (FEMP) EPEAT^O Gold registered in the United States. See http://www.epeat.net for registration status in your country. TCO Certified China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label*
Sustainable Impact Specifications	 Product Carbon Footprint (hp.com) Ocean-bound plastic in Speaker 60% post-consumer recycled plastic 65% recycled metal Low halogen Outside Box and corrugated cushions are 100% sustainably sourced and recyclable Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable
System Configuration Energy Consumption	• Bulk packaging available The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".

(in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	5.88 W	6.17 W	5.92 W
Normal Operation (Long idle)	1.66 W	1.85 W	1.76 W
Sleep	1.66 W	1.85 W	1.76 W
Off	0.46 W	0.48 W	0.41 W

NOTE:

Energy efficiency data listed is for an ENERGY STAR[®] compliant product if offered within the model family. HP computers marked with the ENERGY STAR[®] Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR[®] specifications for computers. If a model family does not offer ENERGY STAR[®] compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows[®] operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	20.1 BTU/hr	21.1 BTU/hr	20.2 BTU/hr
Normal Operation (Long idle)	5.7 BTU/hr	6.3 BTU/hr	6.0 BTU/hr
Sleep	5.7 BTU/hr	6.3 BTU/hr	6.0 BTU/hr
Off	1.6 BTU/hr	1.6 BTU/hr	1.4 BTU/hr



***NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)		Sound Power (L _{Wad} , bels)	Sound Pressure (L _{pAm} , decibels)
Typically Configured – Idle		3.1	20.6
Fixed Disk – Random writes		3.3	22.8
Optical Drive – Sequential reads		4.0	31.5
Longevity and Upgrading	•	n be upgraded, possibly exten r components contained in the	nding its useful life by several years. Upgradeable e
	Spare parts are of production.	available throughout the wa	rranty period and or for up to "5" years after the end
Additional Information	directi • This HI Equipr	ive – 2011/65/EC. P product is designed to comp ment (WEEE) Directive – 2002	ne Restrictions of Hazardous Substances (RoHS) oly with the Waste Electrical and Electronic /96/EC. alifornia Proposition 65 (State of California; Safe
	Drinkir • This pr www.e • Plastic and ISO	ng Water and Toxic Enforceme roduct is in compliance with th epeat.net cs parts weighing over 25 grar 01043.	
Packaging Materials	External:	PAPER/Corrugated	220 g
		PAPER/Corrugated	49 g
		PAPER/Molded Pulp	52 g
		PAPER/Molded Pulp	56 g
		PAPER/Paper	3 g
	Internal:	PLASTIC/Polyethylene low	
	The plastic pa	ckaging material contains at l	east 0.0% recycled content.
	The corrugate	d paper packaging materials (contains at least 59.1% recycled content.
RoHS Compliance	the restrictions to our products	in the European Union (EU) R	ons. We were among the first companies to extend estriction of Hazardous Substances (RoHS) Directive SE. HP has contributed to the development of a, India, and Vietnam.
	wide eliminatio substances—in	on of substances of concern. W	vs play an important role in promoting industry- Ve have supported the inclusion of additional n phthalates—in future RoHS legislation that :s.
	requirements for	or virtually all relevant produ	orldwide compliance with the new EU RoHS cts by July 2013, and we will continue to extend the restricted substances as regulations continue to



To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
 - Reduce size and weight of packages to improve transportation fuel efficiency.
 - Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and
RecyclingHP offers end-of-life HP product return and recycling programs in many geographic areas. To
recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest
HP sales office. Products returned to HP will be recycled, recovered or disposed of in a
responsible manner.



	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers . These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP Inc. Corporate Environmental Information	For more information about HP's commitment to the environment:
	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
Footnotes	 Percentage of ocean-bound plastic contained in each component varies by product Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard. External power supplies, WWAN modules, power cords, cables and peripherals excluded. 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers. Fiber cushions made from 100% recycled wood fiber and organic materials. Plastic cushions are made from >90% recycled plastic.

QuickSpecs

(III)

Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part #
Audio/Video	HP USB G2 Stereo Headset	428H5AA
	HP USB G2 Stereo Headset	428K6AA
	HP 3.5mm G2 Stereo Headset	428H6AA
	HP 3.5mm G2 Stereo Headset	428K7AA
	HP 365 BT Speaker	567D3AA
	HP 325 FHD USB-A Webcam	53X27AA
	HP 965 4K Streaming Webcam	695J5AA
	HP 625 FHD Webcam	6Y7L1AA
Cases	HP Prelude 15.6 Backpack (Bulk Qty.15)	1E7D6A6
	HP Prelude Pro Recycle Backpack	1X644AA
	HP Prelude Pro Recycle Top Load	1X645AA
	HP Prelude 15.6 Top Load	1E7D7AA
	HP Prelude 15.6 Top Load	2Z8P4AA
	HP Prelude 15.6 Top Load	50P31AA
	HP Prelude 15.6 Backpack	1E7D6AA
	HP Prelude 15.6 Backpack	2Z8P3AA
	HP Prelude 15.6 Backpack	50P32AA
	HP Prelude Pro Recycled 15.6 Backpack (Bulk Qty.12)	1X644A6
	HP Prelude Pro Recycled 15.6 Top Load (Bulk Qty.12)	1X645A6
	HP Renew Business 17.3 Laptop Backpack	3E2U5AA
	HP Renew Business 17.3 Laptop Bag	3E2U6AA
	HP Renew Business 15.6 Laptop Bag	3E5F8AA
	HP Renew Business 14.1 Laptop Bag	3E5F9AA
	HP Renew Business 14.1 Laptop Sleeve	3E2U7AA
	HP Renew Business 17.3 Laptop Backpack (Bulk Qty. 6)	3E2U5A6
	HP Renew Business 15.6 Laptop Bag (Bulk Qty.12)	3E5F8A6
	HP Renew Business 14.1 Laptop Bag (Bulk Qty.12)	3E5F9A6
	HP Renew Business 14.1 Sleeve (Bulk Qty. 24)	3E2U7A6
	HP Renew Executive 16 Laptop Backpack	6B8Y1AA
	HP Renew Executive 16 Laptop Bag	6B8Y2AA
	HP Renew Executive 14.1 Laptop Sleeve	6B8Y3AA
	HP Travel 25 Liter 15.6 Iron Gray Laptop Backpack	6B8U4AA
	HP Travel 25 Liter 15.6 Iron Gray Laptop Backpack	6H2D8AA
	HP Travel 18 Liter 15.6 Iron Gray Laptop Backpack	6B8U6AA
	HP Travel 18 Liter 15.6 Iron Gray Laptop Backpack	6H2D9AA
Docking station	HP USB-C Dock G5	26D32AA
	HP USB-C Dock G5	5TW10AA
	HP USB-C/A Universal Dock G2	5TW13AA
	HP Thunderbolt 120W G4 Dock	4J0A2AA
	HP Thunderbolt 280W G4 Dock w/Combo Cable	4JOG4AA
	HP USB-C G5 Essential Dock	72C71AA

Options and Accessories (sold separately and availability may vary by country)

Dongle	HP HDMI to VGA Adapter	H4F02AA
-	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP USB-C to DisplayPort Adapter	N9K78AA
	HP USB-C to VGA Adapter	N9K76AA
	HP USB-C to VGA Adapter	P7Z54AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
	HP USB-C to HDMI 2.0 Adapter	2PC54AA
	HP USB-C to RJ45 Adapter G2	4Z527AA
	HP USB-C to RJ45 Adapter G2	4Z534AA
	HP USB 3.0 to Gig RJ45 Adapter G2	4Z7Z7AA
	HP USB-C to DisplayPort Adapter G2	8Y8Y1AA
Hub	HP USB-C Travel Hub G2	7PJ38AA
	HP USB-C to USB-A Hub	Z6A00AA
	HP Universal USB-C Multiport Hub	50H55AA
	HP Universal USB-C Multiport Hub	50H98AA
	HP 4K USB-C Multiport Hub	6G842AA
	HP 4K USB-C Multiport Hub	6G843AA
	HP Universal USB-C Hub and Laptop Charger Combo	9H0H9AA
Keyboard/Combo	HP 320K Wired Keyboard	9SR37A4
	HP 975 USB+BT Dual-Mode Wireless Keyboard	3Z726AA
	HP 455 Programmable Wireless Keyboard	4R177AA
	HP 965 BLK Ergonomic Wireless Keyboard	7E756AA
	HP 475 Dual-Mode Wireless Keyboard	7N7B9AA
	HP 405 Multi-Device Backlit Wired Keyboard	7N7C1AA
	HP 435 Programmable Bluetooth Wireless Keypad	7N7C3AA
	HP Wireless Rechargeable 950MK Mouse and Keyboard	3M165AA
	HP Wired Desktop 320MK Mouse and Keyboard	9SR36AA
	HP 655 Wireless Keyboard and Mouse Combo	4R009AA
Mouse	HP Wired 320M Mouse	9VA80AP
	HP Premium Wireless Mouse	1JR31AA
	HP Travel Bluetooth Mouse	6SP30AA
	HP Multi-Device 635 Black Wireless Mouse	1DOK2AA
	HP Creator 935 Black Wireless Mouse	1DOK8AA
	HP 235 Slim Wireless Mouse	4E407AA
	HP 435 Multi-Device Wireless Mouse	3B4Q5AA
	HP 715 Rechargeable Multi-Device Bluetooth Mouse	6E6F0AA
	HP 925 Ergonomic Vertical Wireless Mouse	6H1A5AA
Power	HP 65W USB-C LC Power Adapter	1РЗК6АА
	HP 65W USB-C LC Power Adapter	944V0AA



QuickSpecs

Options and Accessories (sold separately and availability may vary by country)

•		-
	HP 65W Gallium Nitride USB-C Laptop Charger	600Q7AA
	HP 65W Gallium Nitride USB-C Laptop Charger	600Q8AA
	HP 65W USB-C Laptop Charger	671R2AA
	HP 65W USB-C Laptop Charger	671R3AA
	HP 110W USB-C Laptop Charger	8B3Y2AA
Commodity	HP 2TB PCIe-4x4 NVMe TLC M.2 Solid State Drive	6D8L6AA
	HP USB External DVDRW Drive	F2B56AA
	HP USB External DVDRW Drive	Y3T76AA
Security	HP Nano Keyed Cable Lock	1AJ39AA
	HP Nano Keyed Cable Lock	1AJ39UT
	HP Nano Master Keyed Cable Lock	1AJ40AA
	HP Sure Key Cable Lock	6UW42AA
	HP Nano Combination Cable Lock	63B28AA
	HP Essential Nano Combination Cable Lock	63B31AA
Monitor	HP Z38c 37.5-inch Curved Display	Z4W65A4
	HP Z38c 37.5-inch Curved Display	Z4W65A7
	HP Z38c 37.5-inch Curved Display	Z4W65A8
	HP Z38c 37.5-inch Curved Display	Z4W65AT
	HP Z27k G3 4K USB-C Display	1B9T0A7
	HP Z27k G3 4K USB-C Display	1B9T0AA
	HP Z27k G3 4K USB-C Display	1B9T0AT
	HP Z27u G3 QHD USB-C Display	1B9X2A7
	HP Z27u G3 QHD USB-C Display	1B9X2AA
	HP Z27u G3 QHD USB-C Display	1B9X2AT
	HP Z24u G3 WUXGA USB-C Display	1C4Z6A7
	HP Z24u G3 WUXGA USB-C Display	1C4Z6AA
	HP Z24u G3 WUXGA USB-C Display	1C4Z6AT
	HP Z24u G3 WUXGA USB-C Display	1C4Z6E9
	HP Z24q G3 QHD Display	4Q8N4A7
	HP Z24q G3 QHD Display	4Q8N4AA
	HP Z24q G3 QHD Display	4Q8N4AT
	HP Z24q G3 QHD Display	4Q8N4E9
	HP Z24m G3 QHD Conferencing Display	4Q8N9A7
	HP Z24m G3 QHD Conferencing Display	4Q8N9AA
	HP Z24m G3 QHD Conferencing Display	4Q8N9AT
	HP Z24m G3 QHD Conferencing Display	4Q8N9E9
	HP Z32k G3 4K USB-C Display	50U19A7
	HP Z32k G3 4K USB-C Display	50U19AA
	HP Z32k G3 4K USB-C Display	50U19AT
	HP Z32k G3 4K USB-C Display	50U19E9



Copyright © 2024 HP Development Company, L.P. The information contained herein is subject to change without notice. The only warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.

Intel, Core, and Celeron, Thunderbolt and vPro are registered trademarks or trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries. Bluetooth is a registered trademark of its proprietor used by HP Inc. under license. AMD, FirePro, and Enduro are trademarks of Advanced Micro Devices, Inc. Adobe is a trademark of Adobe Systems Incorporated. Microsoft and Windows are U.S. registered trademarks of Microsoft Corporation in the United States and/or other countries. Qualcomm and Snapdragon are trademarks of Qualcomm, Inc. SD, SDHC, and SDXC are trademarks of USB Implementers Forum. ENERGY STAR[®] is a registered trademark mark of the U.S. Environmental Protection Agency.

Date of change:	Version History:		Description of change:
March 12, 2024	From v1 to v2	Changed	POWER section
March 25, 2024	From v2 to v3	Changed Page 1 Right image	
April 8, 2024	From v3 to v4	Changed	Format
April 24, 2024	From v4 to v5	Changed	WEIGHTS & DIMENSIONS, POWER sections
May 22, 2024	From v5 to v6	Changed	HDMI support
July 18, 2024	From v6 to v7	Changed	At A Glance, DISPLAY, SOFTWARE AND SECURITY sections
July 18, 2024	From v7 to v8	Changed	POWER section
July 18, 2024	From v8 to v9	Changed	SOFTWARE AND SECURITY section
September 26, 2024	From v9 to v10	Changed	Format
October 17, 2024	From v10 to v11	Changed	GRAPHICS section

